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MS AF, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Dated: September 27, 2007

Signature: *R. Kafer*

(Rabiyah S. Kafer)

EXPEDITED PROCEDURE
Group Art Unit: 2814
Docket No.: TIMI 3.0-003

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re. Patent Application of: :
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Iijima et al. :
:
Application No.: 10/812,349 : Group Art Unit: 2814
:
:
Filed: March 30, 2004 : Examiner: T. X. Le
:
:
For: WIRING CIRCUIT BOARD, :
:
MANUFACTURING METHOD FOR THE :
:
WIRING CIRCUIT BOARD, AND :
:
CIRCUIT MODULE :
:

RESPONSE UNDER 37 CFR 1.116

MS AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In response to the Office Action dated April 27, 2007,
finally rejecting claims 52-59, please amend the
above-identified U.S. patent application as follows: